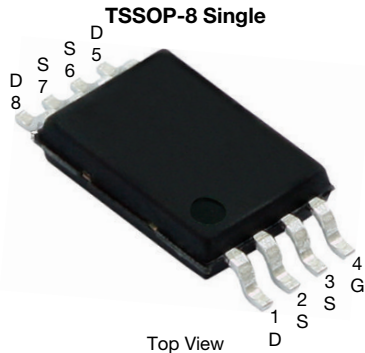


P-Channel 20 V (D-S) MOSFET



Top View

FEATURES

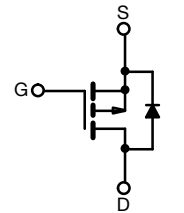
- TrenchFET® power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Load switch
- Battery switch
- Power management



P-Channel MOSFET

PRODUCT SUMMARY

V _{DS} (V)	-20
R _{DS(on)} max. (Ω) at V _{GS} = -4.5 V	0.0098
R _{DS(on)} max. (Ω) at V _{GS} = -2.5 V	0.0130
R _{DS(on)} max. (Ω) at V _{GS} = -1.8 V	0.0227
Q _g typ. (nC)	63
I _D (A) ^d	-12.5
Configuration	Single

ORDERING INFORMATION

Package	TSSOP-8
Lead (Pb)-free and halogen-free	Si6423ADQ-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	V _{DS}	-20	V	
Gate-source voltage	V _{GS}	± 8		
Continuous drain current (T _J = 150 °C) ^a	I _D	T _C = 25 °C	-12.5	
		T _C = 70 °C	-10	
		T _A = 25 °C	-10.3 ^{a, b}	
		T _A = 70 °C	-8.2 ^{a, b}	
Pulsed drain current (t = 300 μs)	I _{DM}	-70	A	
Continuous source-drain diode current	I _S	T _C = 25 °C		-1.9
		T _A = 25 °C		-1.3
Avalanche current	I _{AS}	-20		mJ
Single pulse avalanche energy	E _{AS}	20		
Maximum power dissipation	P _D	T _C = 25 °C	2.2	
		T _C = 70 °C	1.4	
		T _A = 25 °C	1.5 ^{a, b}	
		T _A = 70 °C	1.0 ^{a, b}	
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^{a, c}	R _{thJA}	65	83	°C/W
Maximum junction-to-case (drain)	R _{thJC}	46	56	

Notes

- Surface mounted on 1" x 1" FR4 board
- t = 10 s
- Maximum under steady state conditions is 120 °C/W
- T_C = 25 °C



SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = -250\text{ }\mu\text{A}$	-20	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	$I_D = -250\text{ }\mu\text{A}$	-	-11	-	mV/ $^\circ\text{C}$
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$		-	2.9	-	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250\text{ }\mu\text{A}$	-0.4	-	-1	V
Gate-source leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 8\text{ V}$	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -20\text{ V}$, $V_{GS} = 0\text{ V}$	-	-	-1	μA
		$V_{DS} = -20\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 55\text{ }^\circ\text{C}$	-	-	-10	
On-state drain current ^a	$I_{D(on)}$	$V_{DS} \leq -5\text{ V}$, $V_{GS} = -10\text{ V}$	-10	-	-	A
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}$, $I_D = -10\text{ A}$	-	0.0082	0.0098	Ω
		$V_{GS} = -2.5\text{ V}$, $I_D = -8\text{ A}$	-	0.0108	0.0130	
		$V_{GS} = -1.8\text{ V}$, $I_D = -5\text{ A}$	-	0.0175	0.0227	
Forward transconductance ^a	g_{fs}	$V_{DS} = -10\text{ V}$, $I_D = -10\text{ A}$	-	70	-	S
Dynamic ^b						
Input capacitance	C_{iss}	$V_{DS} = -10\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$	-	5875	-	pF
Output capacitance	C_{oss}		-	540	-	
Reverse transfer capacitance	C_{rss}		-	555	-	
Total gate charge	Q_g	$V_{DS} = -10\text{ V}$, $V_{GS} = -8\text{ V}$, $I_D = -16.7\text{ A}$	-	112	168	nC
			$V_{DS} = -10\text{ V}$, $V_{GS} = -4.5\text{ V}$, $I_D = -16.7\text{ A}$	-	63	
Gate-source charge	Q_{gs}	$V_{DS} = -10\text{ V}$, $V_{GS} = -4.5\text{ V}$, $I_D = -16.7\text{ A}$	-	8.7	-	
Gate-drain charge	Q_{gd}		-	25.3	-	
Gate resistance	R_g	$f = 1\text{ MHz}$	0.8	3.6	7.2	Ω
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -10\text{ V}$, $R_L = 1\text{ }\Omega$, $I_D \cong -10\text{ A}$, $V_{GEN} = -8\text{ V}$, $R_g = 1\text{ }\Omega$	-	12	24	ns
Rise time	t_r		-	4	8	
Turn-off delay time	$t_{d(off)}$		-	120	180	
Fall time	t_f		-	36	54	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	$T_C = 25\text{ }^\circ\text{C}$	-	-	-18	A
Pulse diode forward current ^a	I_{SM}		-	-	-70	
Body diode voltage	V_{SD}	$I_S = -10\text{ A}$	-	-0.75	-1.2	V
Body diode reverse recovery time	t_{rr}	$I_F = -10\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^\circ\text{C}$	-	45	68	ns
Body diode reverse recovery charge	Q_{rr}		-	38	57	nC
Reverse recovery fall time	t_a		-	18	-	ns
Reverse recovery rise time	t_b		-	27	-	

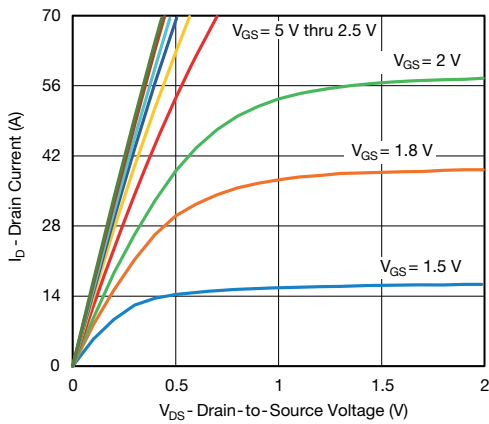
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

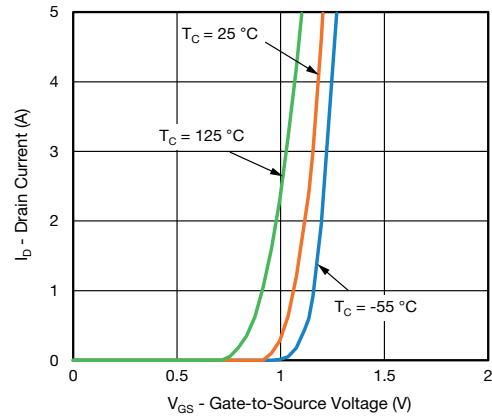
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



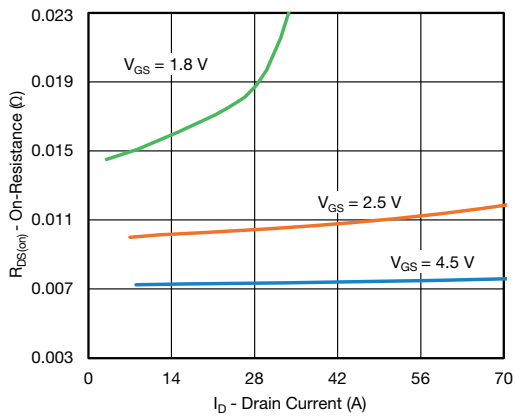
TYPICAL CHARACTERISTICS (T_J = 25 °C, unless otherwise noted)



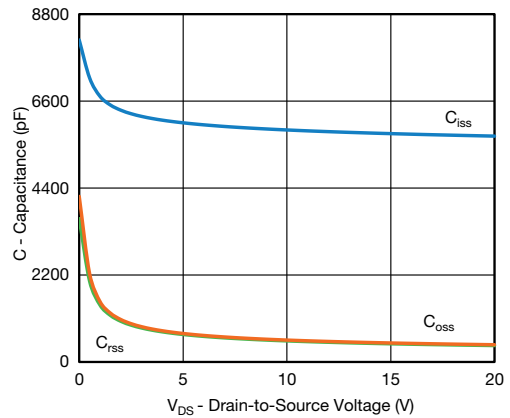
Output Characteristics



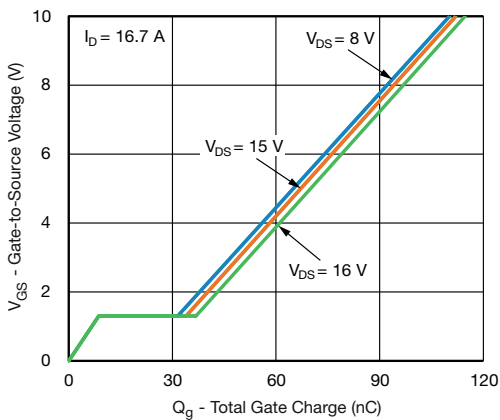
Transfer Characteristics



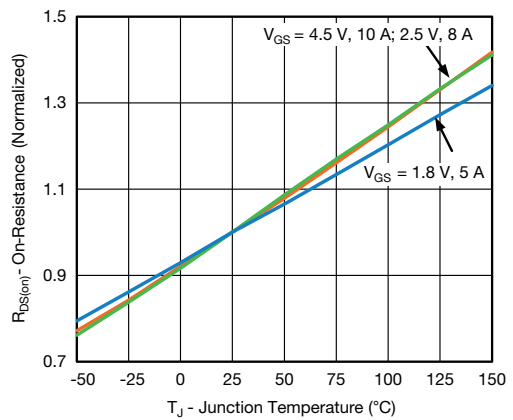
On-Resistance vs. Drain Current



Capacitance



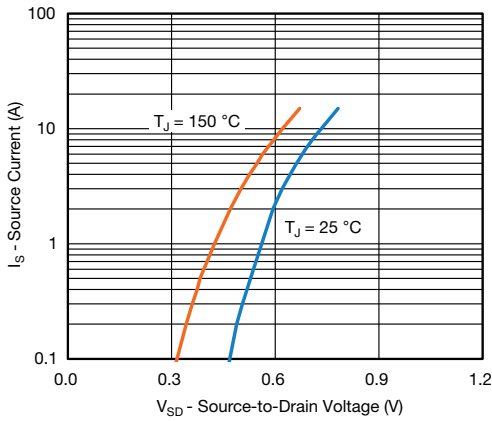
Gate Charge



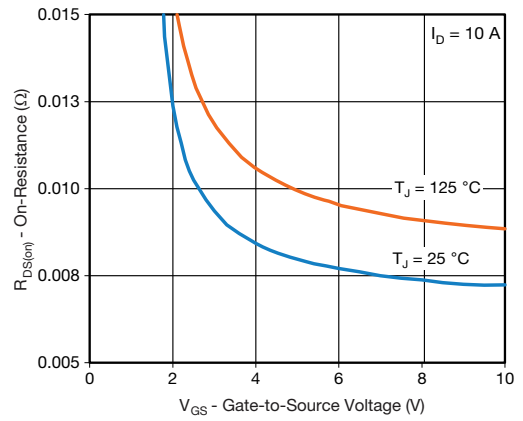
Normalized On-Resistance vs. Junction Temperature



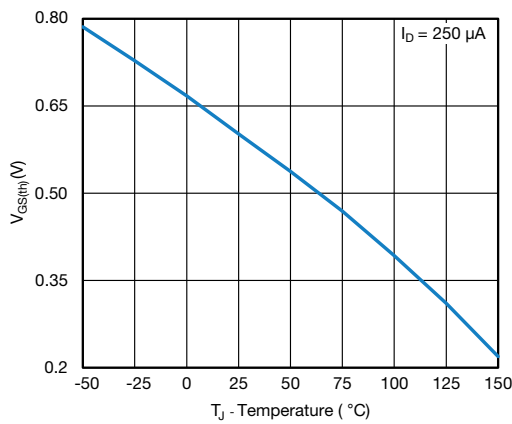
TYPICAL CHARACTERISTICS (T_J = 25 °C, unless otherwise noted)



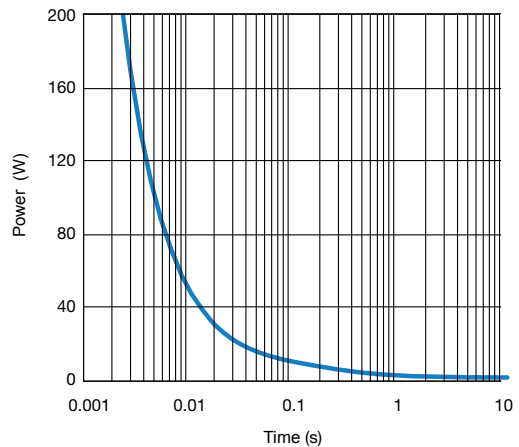
Source-Drain Diode Forward Voltage



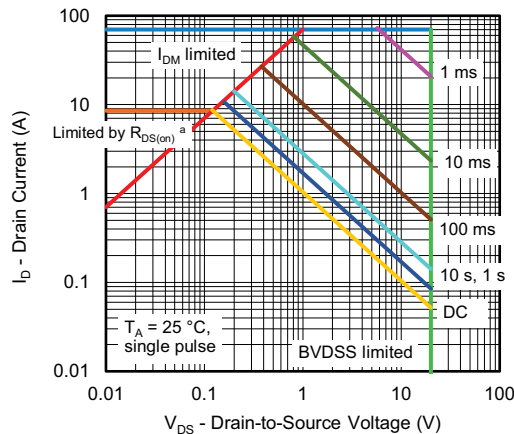
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



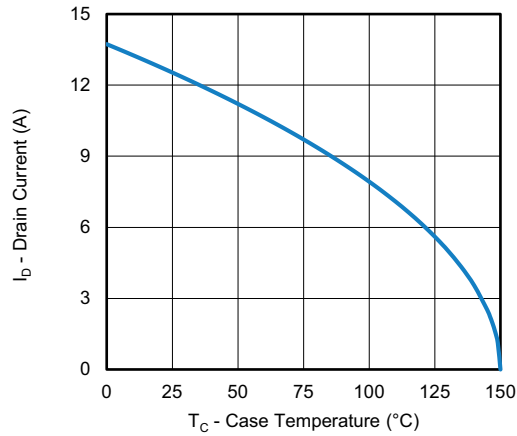
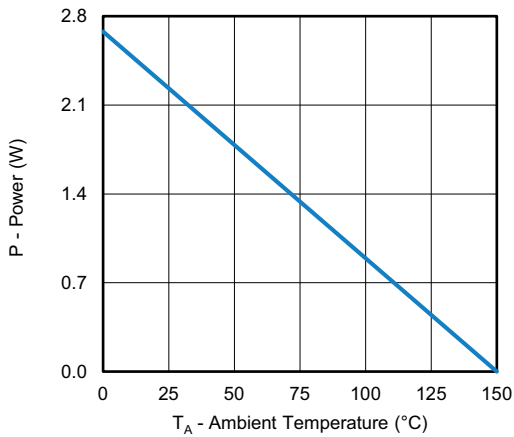
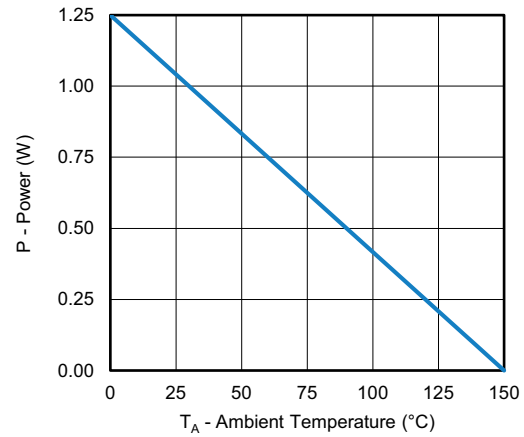
Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

Note

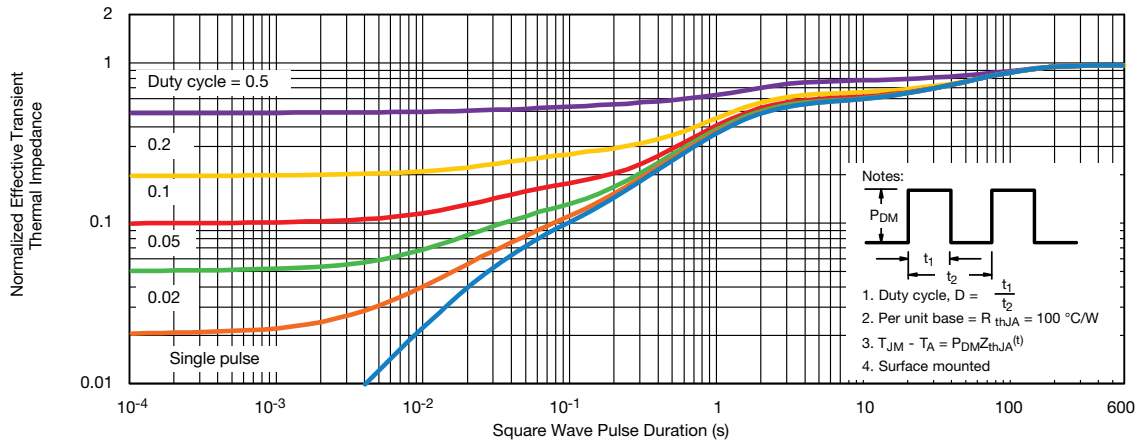
a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

TYPICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)

Current Derating ^a

Power, Junction-to-Case

Power, Junction-to-Ambient
Note

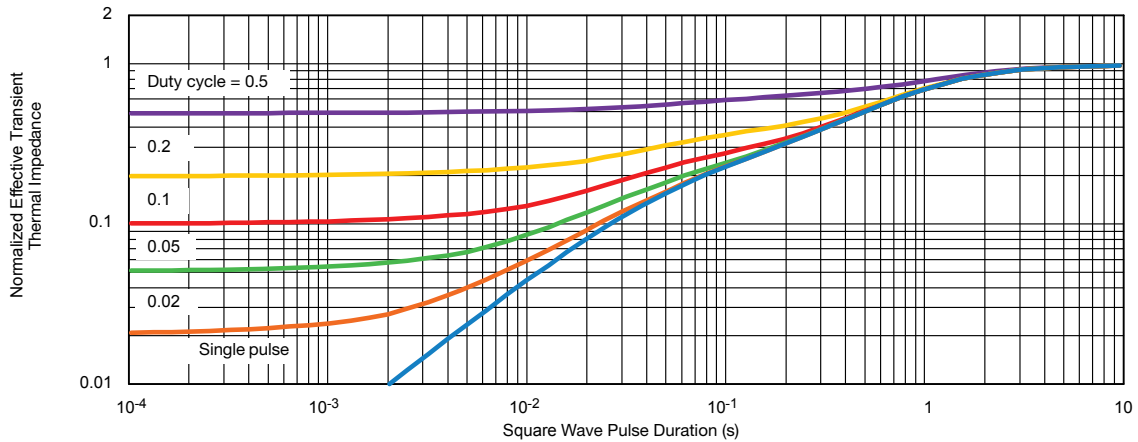
- a. The power dissipation P_D is based on T_J max. = 150 $^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (T_J = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



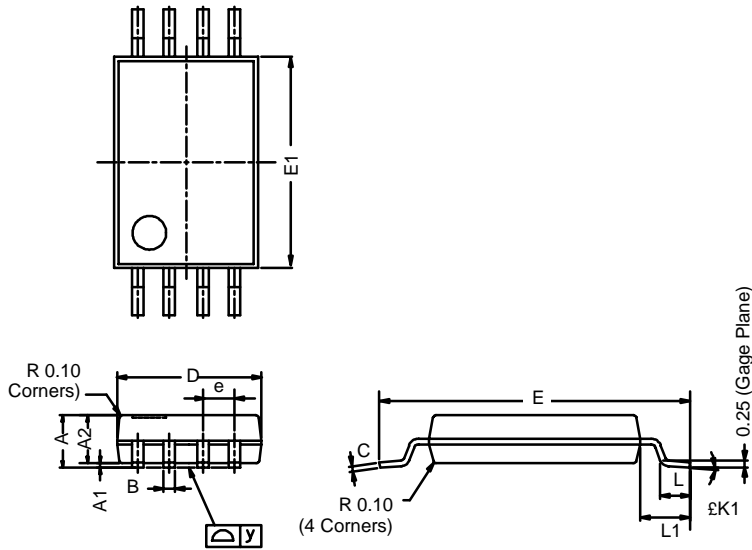
Normalized Thermal Transient Impedance, Junction-to-Case

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TSSOP: 8-LEAD

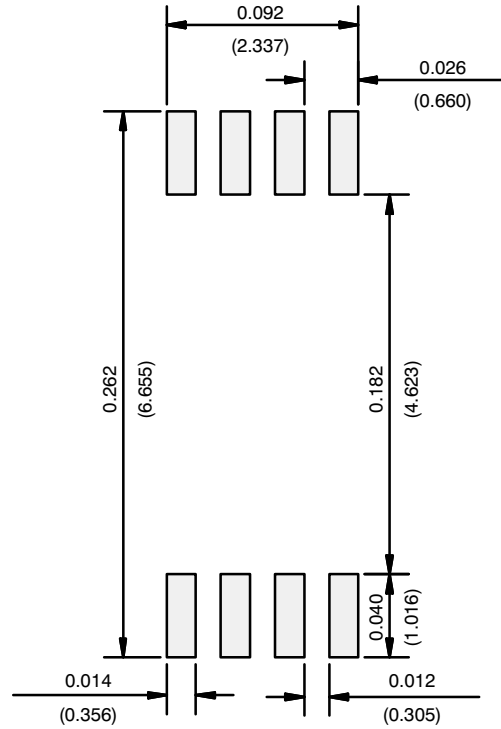
JEDEC Part Number: MO-153



Dim	MILLIMETERS		
	Min	Nom	Max
A	–	–	1.20
A ₁	0.05	0.10	0.15
A ₂	0.80	1.00	1.05
B	0.19	0.28	0.30
C	–	0.127	–
D	2.90	3.00	3.10
E	6.20	6.40	6.60
E ₁	4.30	4.40	4.50
e	–	0.65	–
L	0.45	0.60	0.75
L ₁	0.90	1.00	1.10
Y	–	–	0.10
£K1	0°	3°	6°

ECN: S-03946—Rev. G, 09-Jul-01
DWG: 5844

RECOMMENDED MINIMUM PADS FOR TSSOP-8



Recommended Minimum Pads
Dimensions in Inches/(mm)

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